

5.0X6.0mm SURFACE MOUNT LED LAMP

PRELIMINARY SPEC

Part Number: AA5060SEC/J3

Hyper Orange

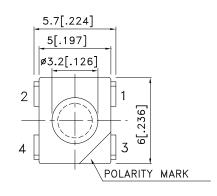
Features

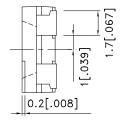
- Single color.
- Suitable for all SMT assembly and solder process.
- Available on tape and reel.
- Ideal for backlighting.
- Package: 500pcs / reel.
- Moisture sensitivity level : level 4.
- RoHS compliant.

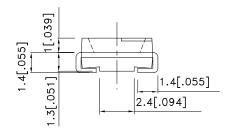
Description

The Hyper Orange device is based on light emitting diode chip made from AllnGaP.

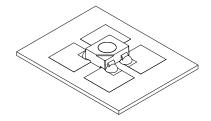
Package Dimensions











- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
- 3. Specifications are subject to change without notice.4. The device has a single mounting surface. The device must be mounted according to the specifications.





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Selection Guide

Part No.	Dice	Lens Type	lv (mcd) [2] @ 50mA		Viewing Angle [1]
		2.	Min.	Тур.	201/2
AA5060SEC/J3	Hyper Orange (AllnGaP)	WATER CLEAR	3300	4500	100°

- 1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value. 2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Hyper Orange	640		nm	IF=20mA
λD [1]	Dominant Wavelength	Hyper Orange	630		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Hyper Orange	25		nm	IF=20mA
С	Capacitance	Hyper Orange	27		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Hyper Orange	2.2	2.8	V	I=20mA
lR	Reverse Current	Hyper Orange		10	uA	V _R =5V

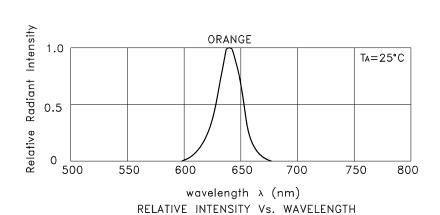
Notes: 1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

arameter Hyper Orange		Units	
Power dissipation	140	mW	
DC Forward Current	50	mA	
Peak Forward Current [1]	150	mA	
Reverse Voltage	5	V	
Operating Temperature	-40°C To +85°C		
Storage Temperature	-40°C To +85°C		

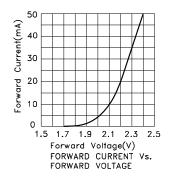
Note: 1. 1/10 Duty Cycle, 0.1ms Pulse Width.

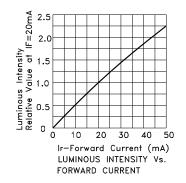
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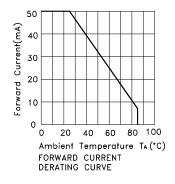


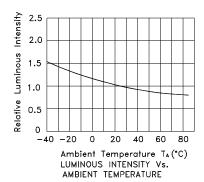
Hyper Orange

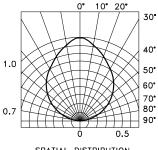
AA5060SEC/J3











SPATIAL DISTRIBUTION

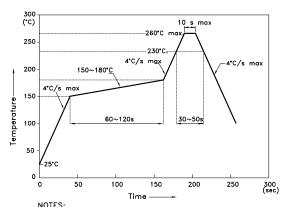
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Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



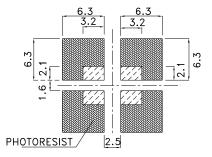
NOTES:

1.We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.

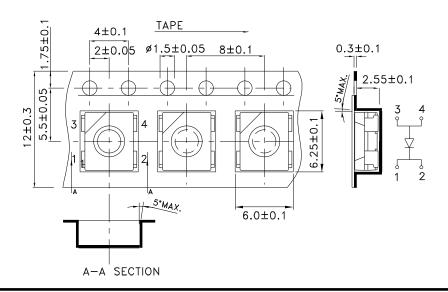
2.Don't cause stress to the epoxy resin while it is exposed to high temperature.

3.Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)

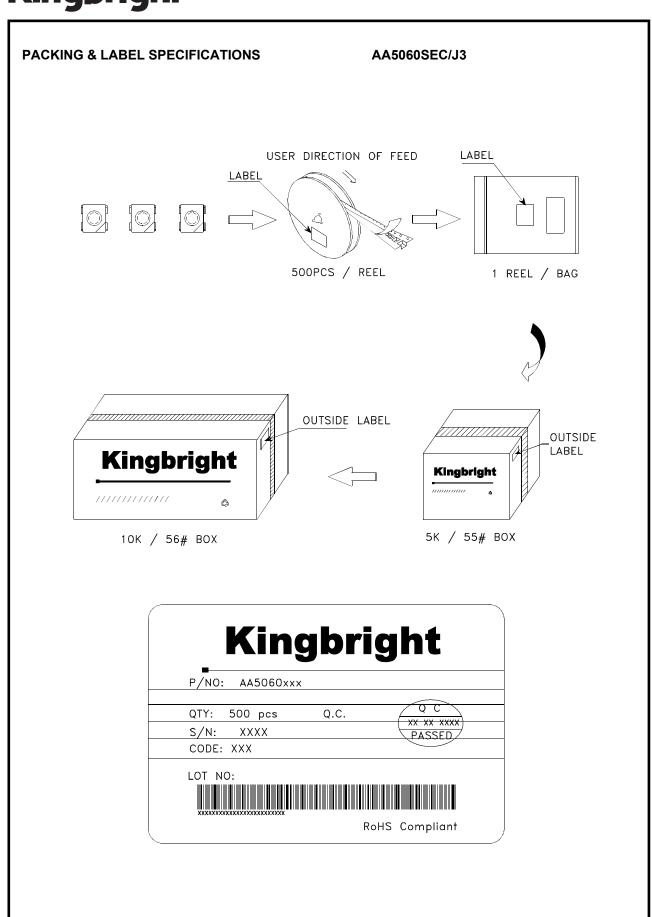


Tape Dimensions (Units: mm)



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